

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming Hsien TSAI</td> <td>02/16/2011</td> </tr> <tr> <td>Jun-De JIN</td> <td>02/16/2011</td> </tr> <tr> <td>Hsieh-Hung HSIEH</td> <td>02/16/2011</td> </tr> <tr> <td>Tzu-Jin YEH</td> <td>02/16/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ming Hsien TSAI	02/16/2011	Jun-De JIN	02/16/2011	Hsieh-Hung HSIEH	02/16/2011	Tzu-Jin YEH	02/16/2011
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Tzu-Jin YEH	02/16/2011										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.										
Street Address:	No. 8, Li-Hsin Road 6										
Internal Address:	Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13029240</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13029240						
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CORRESPONDENCE DATA											
Fax Number:	(215)689-4921										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	N1085-00763										
NAME OF SUBMITTER:	Jarrad M. Gunther										

CH \$40.00 13029240

Total Attachments: 3

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Serial No. 13/029,240
filed February 17,
2011

ATTORNEY DOCKET NO.: 2010.1246/1085.763

ASSIGNMENT AND AGREEMENT

For value received, we, **Ming Hsien Tsai, Jun-De Jin, Hsieh-Hung Hsieh and Tzu-Jin Yeh**, hereby transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **ESD BLOCK ISOLATION BY RF CHOKE** described in a non-provisional application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 2011/Feb./16

Ming-Hsien Tsai
Ming Hsien TSAI

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Inventor No. 2

Dated: 2011/Feb./16

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Jun-De JIN

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No. 3

Dated: 2011/Feb./16

Hsieh-Hung Hsieh
Hsieh-Hung HSIEH

Residence:

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ATTORNEY DOCKET NO.: 2010.1246/1085.763

No. 4

Dated: Feb 16, 2011

Tzu-Jin Yeh

Tzu-Jin YEH

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R.O.C.**

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RECORDED: 02/17/2011

PATENT
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